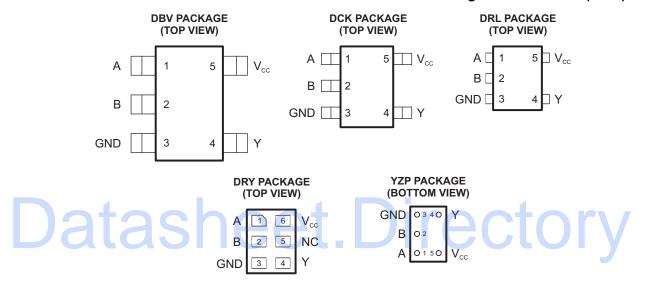


#### **FEATURES**

- Available in the Texas Instruments
   NanoStar<sup>™</sup> and NanoFree<sup>™</sup> Packages
- Supports 5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 3.6 ns at 3.3 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ± 24-mA Output Drive at 3.3 V

- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



NC – No internal connection
See mechanical drawings for dimensions.

#### **DESCRIPTION/ORDERING INFORMATION**

This single 2-input positive-OR gate is designed for 1.65-V to 5.5-V V<sub>CC</sub> operation.

The SN74LVC1G32 performs the Boolean function  $Y = A + B \text{ or } Y = \overline{A \cdot B}$  in positive logic.

NanoStar<sup>™</sup> and NanoFree<sup>™</sup> package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.



#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)	Reel of 3000	SN74LVC1G32YZPR	CG_
	SON - DRY	Reel of 5000	SN74LVC1G32DRYR	CG_
			SN74LVC1G32DBVR	
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G32DBVRE4	C22
			SN74LVC1G32DBVRG4	C32_
		Tube of 250	SN74LVC1G32DBVT	
–40°C to 85°C		Reel of 3000	SN74LVC1G32DCKR	
			SN74LVC1G32DCKRE4	
	SOT (SC-70) – DCK		SN74LVC1G32DCKRG4	CG_
		Tube of 250	SN74LVC1G32DCKT	
		Tube 01 250	SN74LVC1G32DCKTE4	
	SOT (SOT 553) DDI	Reel of 4000	SN74LVC1G32DRLR	CG
	SOT (SOT-553) – DRL	Reel of 4000	SN74LVC1G32DRLRG4	CG_

- Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
   DBV/DCK/DRL/DRY: The actual top-side marking has one additional character that designates the assembly/test site.
- (2) DBV/DCK/DRLY: The actual top-side marking has one additional character that designates the assembly/test site. YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, = Pb-free).

#### **FUNCTION TABLE**

INP	OUTPUT	
Α	В	Υ
Н	Х	Н
Х	Н	Н
L	L	L

#### **LOGIC DIAGRAM (POSITIVE LOGIC)**



### SN74LVC1G32 SINGLE 2-INPUT POSITIVE-OR GATE

SCES2190-APRIL 1999-REVISED FEBRUARY 2007

# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	6.5	V
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the	he high or low state (2)(3)	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous ouput current		±50	mA	
	Continuous current through V <sub>CC</sub> or GND	)		±100	mA
		DBV package		206	
		DCK package		252	
$\theta_{JA}$	Package thermal impedance (4)	DRL package		142	°C/W
		DRY package		234	
		YZP package		132	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>(2)</sup> The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>3)</sup> The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

## SN74LVC1G32 SINGLE 2-INPUT POSITIVE-OR GATE

SCES2190-APRIL 1999-REVISED FEBRUARY 2007



# Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
.,	Complexed to a co	Operating	1.65	5.5	V	
$V_{CC}$	Supply voltage	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
.,	High level inner valence	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$			V	
$V_{IH}$	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	2		V	
		V <sub>CC</sub> = 4.5 V to 5.5 V	$0.7 \times V_{CC}$			
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V	Low lovel input valtage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		0.8	V	
		V <sub>CC</sub> = 4.5 V to 5.5 V		$0.3 \times V_{CC}$		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	$V_{CC}$	V	
		V <sub>CC</sub> = 1.65 V		-4		
		V <sub>CC</sub> = 2.3 V		-8		
$I_{OH}$	High-level output current	el output current		-16	mA	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 4.5 V		-32		
		V <sub>CC</sub> = 1.65 V		4		
		V <sub>CC</sub> = 2.3 V		8		
$I_{OL}$	Low-level output current	V 2V		16	mA	
		V <sub>CC</sub> = 3 V		24		
		V <sub>CC</sub> = 4.5 V		32		
		$V_{CC}$ = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20		
Δt/Δν	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		5		
T <sub>A</sub>	Operating free-air temperature	·	-40	85	°C	

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN TYP(1)	MAX	UNIT	
	$I_{OH} = -100 \mu A$	1.65 V to 5.5 V	V <sub>CC</sub> – 0.1			
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		V	
V <sub>OH</sub>	$I_{OH} = -16 \text{ mA}$	3 V	2.4		V	
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			
	$I_{OH} = -32 \text{ mA}$	4.5 V	3.8			
	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V		0.1		
	I <sub>OL</sub> = 4 mA	1.65 V		0.45	).45	
\/	I <sub>OL</sub> = 8 mA	2.3 V		0.3	V	
V <sub>OL</sub>	I <sub>OL</sub> = 16 mA	3 V		0.4	V	
	I <sub>OL</sub> = 24 mA	3 V	0.55			
	I <sub>OL</sub> = 32 mA	4.5 V		0.55		
I <sub>I</sub> A or B inputs	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V		±5	μΑ	
l <sub>off</sub>	$V_I$ or $V_O = 5.5 \text{ V}$	0		±10	μΑ	
I <sub>cc</sub>	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V		10	μΑ	
$\Delta I_{CC}$	One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 5.5 V		500	μΑ	
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V	4		pF	

<sup>(1)</sup> All typical values are at  $V_{CC}$  = 3.3 V,  $T_A$  = 25°C.

### **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 15 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> = 1 ± 0.2		V <sub>CC</sub> = ± 0.3		V <sub>CC</sub> =		UNIT
	(INPOT)		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	Υ	1.9	7.2	0.8	4.4	0.9	3.6	8.0	3.4	ns

#### **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF}$  or 50 pF (unless otherwise noted) (see Figure 2)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1	1.8 V 5 V	V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> = ± 0.3		V <sub>CC</sub> =		UNIT
		(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	t <sub>pd</sub>	A or B	Υ	2.8	8	1.2	5.5	1.1	4.5	1	4	ns

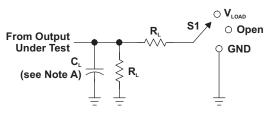
### **Operating Characteristics**

 $T_A = 25^{\circ}C$ 

PARAMETER		TEST	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> = 5 V	UNIT
	FARAMETER	CONDITIONS	TYP	TYP	TYP	TYP	UNII
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	20	20	21	22	pF



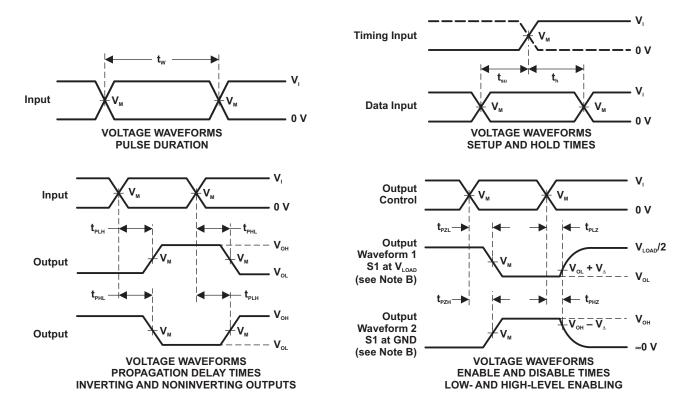
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
$t_{PLZ}/t_{PZL}$	V <sub>LOAD</sub>
$t_{_{\mathrm{PHZ}}}/t_{_{\mathrm{PZH}}}$	GND

LOAD CIRCUIT

	INI	PUTS	V V			-	V,
V <sub>cc</sub>	V,	t,/t,	V <sub>M</sub>	V <sub>M</sub> V <sub>LOAD</sub>		C <sub>L</sub> R <sub>L</sub>	
1.8 V ± 0.15 V	V <sub>cc</sub>	≤2 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	15 pF	<b>1 M</b> Ω	0.15 V
2.5 V ± 0.2 V	V <sub>cc</sub>	≤2 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	15 pF	<b>1 M</b> Ω	0.15 V
3.3 V ± 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	<b>1 M</b> Ω	0.3 V
5 V ± 0.5 V	V <sub>cc</sub>	≤2.5 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	15 pF	<b>1 M</b> Ω	0.3 V



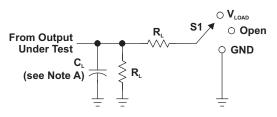
NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>o</sub> = 50  $\Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{\text{PLZ}}$  and  $\dot{t}_{\text{PHZ}}$  are the same as  $t_{\text{dis}}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



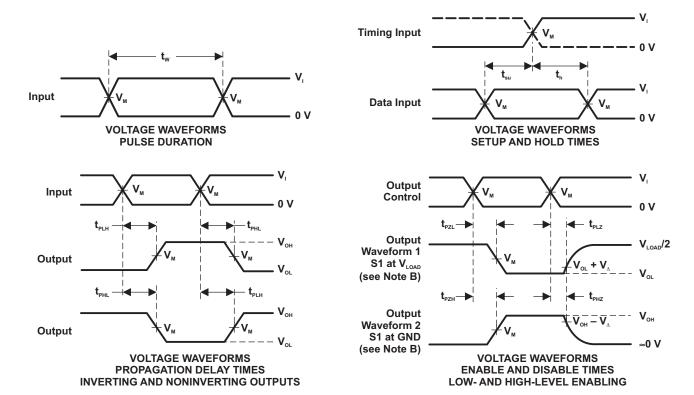
#### PARAMETER MEASUREMENT INFORMATION (continued)



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

LOAD CIRCUIT

	INI	PUTS		v v		-	W
V <sub>cc</sub>	V,	t,/t,	V <sub>M</sub>	<b>V</b> <sub>LOAD</sub>	C <sub>L</sub>	R <sub>L</sub>	V <sub>Δ</sub>
1.8 V ± 0.15 V	V <sub>cc</sub>	≤2 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V ± 0.2 V	V <sub>cc</sub>	≤2 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	30 pF	500 Ω	0.15 V
$3.3~V~\pm~0.3~V$	3 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	V <sub>cc</sub>	≤2.5 ns	V <sub>cc</sub> /2	2 × V <sub>cc</sub>	50 pF	500 Ω	0.3 V



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

  C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z₀ = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{nd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms







#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVC1G32DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DRYR	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32DRYRG4	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G32YZPR	ACTIVE	DSBGA	YZP	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.



#### PACKAGE OPTION ADDENDUM

18-Sep-2008

retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN74LVC1G32:

• Automotive: SN74LVC1G32-Q1

• Enhanced Product: SN74LVC1G32-EP

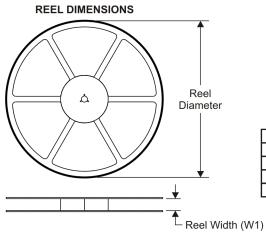
NOTE: Qualified Version Definitions:

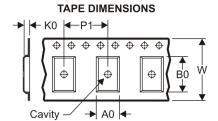
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 22-Sep-2009

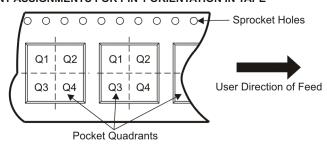
### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nominal	1			i	П							_
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G32DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G32DBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G32DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G32DBVT	SOT-23	DBV	5	250	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G32DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G32DCKR	SC70	DCK	5	3000	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74LVC1G32DCKT	SC70	DCK	5	250	180.0	9.2	2.24	2.34	1.22	4.0	8.0	Q3
SN74LVC1G32DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G32DRLR	SOT	DRL	5	4000	180.0	9.2	1.78	1.78	0.69	4.0	8.0	Q3
SN74LVC1G32DRYR	SON	DRY	6	5000	179.0	8.4	1.2	1.65	0.7	4.0	8.0	Q1
SN74LVC1G32YZPR	DSBGA	YZP	5	3000	180.0	8.4	1.02	1.52	0.63	4.0	8.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G32DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G32DBVR	SOT-23	DBV	5	3000	205.0	200.0	33.0
SN74LVC1G32DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G32DBVT	SOT-23	DBV	5	250	205.0	200.0	33.0
SN74LVC1G32DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74LVC1G32DCKR	SC70	DCK	5	3000	205.0	200.0	33.0
SN74LVC1G32DCKT	SC70	DCK	5	250	205.0	200.0	33.0
SN74LVC1G32DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G32DRLR	SOT	DRL	5	4000	202.0	201.0	28.0
SN74LVC1G32DRYR	SON	DRY	6	5000	220.0	205.0	50.0
SN74LVC1G32YZPR	DSBGA	YZP	5	3000	220.0	220.0	34.0

# DBV (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-178 Variation AA.



# DCK (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



# DRL (R-PDSO-N5)

## PLASTIC SMALL OUTLINE



NOTES:

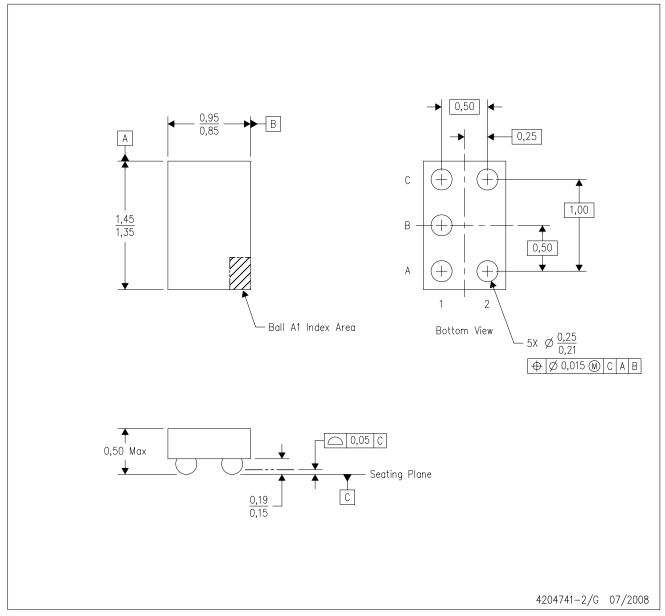
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs.

  Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
- D. JEDEC package registration is pending.



YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY

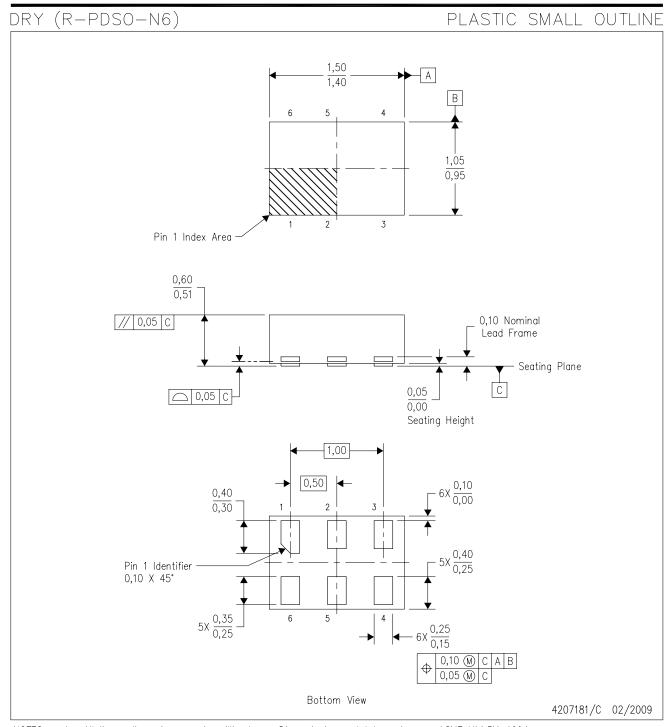


NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. NanoFree  $^{\text{TM}}$  package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. SON (Small Outline No-Lead) package configuration.
- D. This package complies to JÉDEC MO-287 variation UFAD.



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